# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
YUAN YAO	06/20/2008
KAI-LI JIANG	06/20/2008

## **RECEIVING PARTY DATA**

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### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12168845

#### **CORRESPONDENCE DATA**

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PATENT

**REEL: 021201 FRAME: 0721** 

Total Attachments: 2

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> PATENT REEL: 021201 FRAME: 0722

## **ASSIGNMENT**

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1.	Yuan Yao	, residing at	Bei-Jing, China	
2.	Kai-Li Jiang	, residing at	Bei-Jing, China	
3.		, residing at		
4.		, residing at		
5.		, residing at		
		, residing at		

hereby sell(s), assign(s) and transfer(s) unto: Tsinghua University, a university having an office and place of business at No.1,Qinghua Yuan, Haidian District, Beijing City, China, P.R.C. and Hon Hai Precision Ind. Co., LTD. having a principal place of business at 66 Chung Shan Road, Tu-Cheng City, Taipei Hsien, Taiwan, R.O.C. hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as THERMAL INTERFACE MATERIAL HAVING CARBON NANOTUBES, COMPONENT PACKAGE HAVING THE SAME AND METHOD FOR MAKING THE COMPONENT PACKAGE for which the undersigned

[	] previously executed Ser. No.	and filing date of	
[x]i	s executing concurrently herewith		

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

PATENT REEL: 021201 FRAME: 0723

1.	Yuan Yao		Jun.20,2008	
	Yuan Yao	inventor	Date	Witness
2	Kai-Li Jian	9	Jun.20,2008	
	Kai-Li Jiang	J inventor	Date	Witness
3.				
_	<del></del>	inventor	Date	Witness
4		inventor	Date	Witness
		mv onto	Build	VV AMAGO
5		inventor	Date	Witness
6	<del></del>	inventor	Date	Witness
7. <u> </u>	·	inventor	Date	Witness
8				
		inventor	Date	Witness